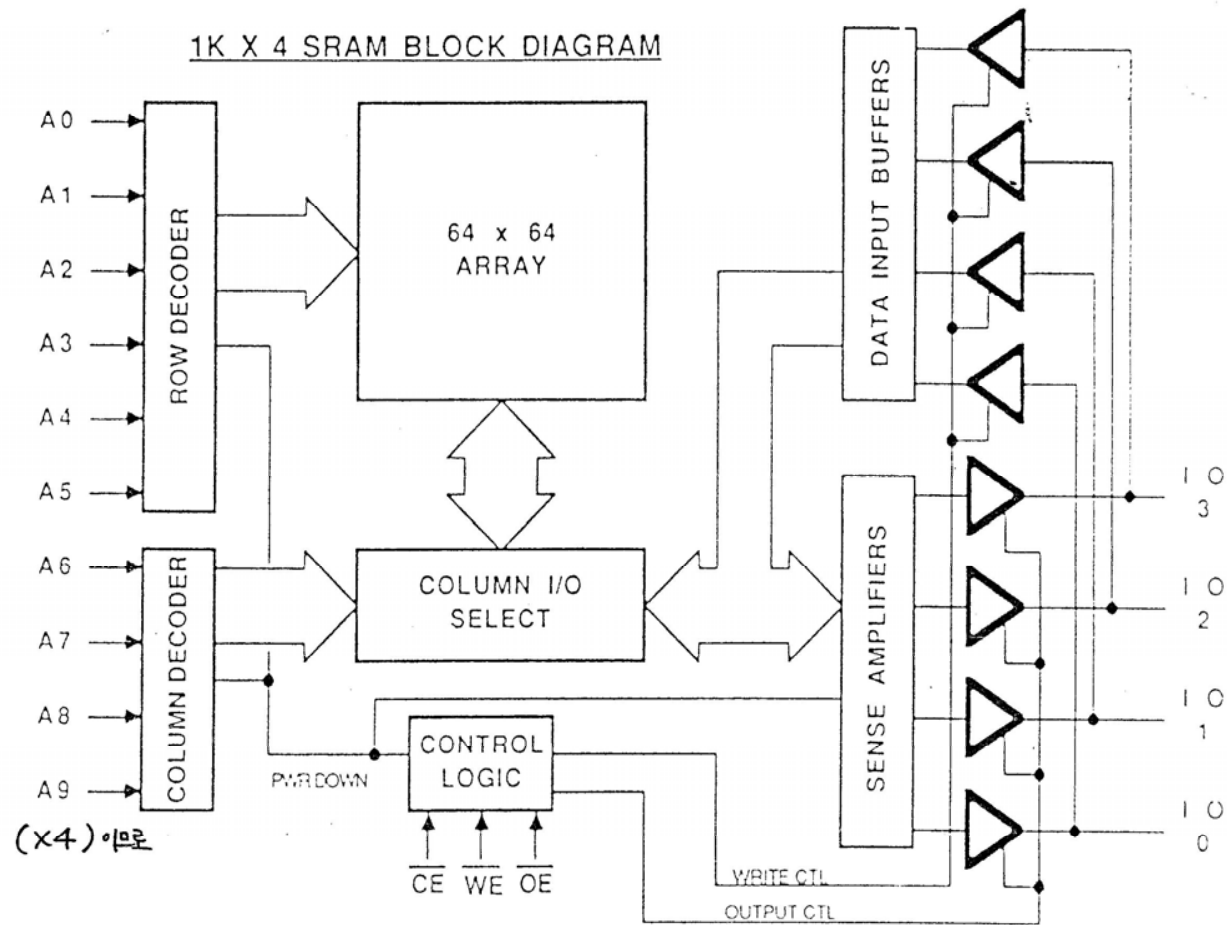


Static Random Access Memories (sRAM)

Instructor - Bruce Bateman, Cypress Semiconductor

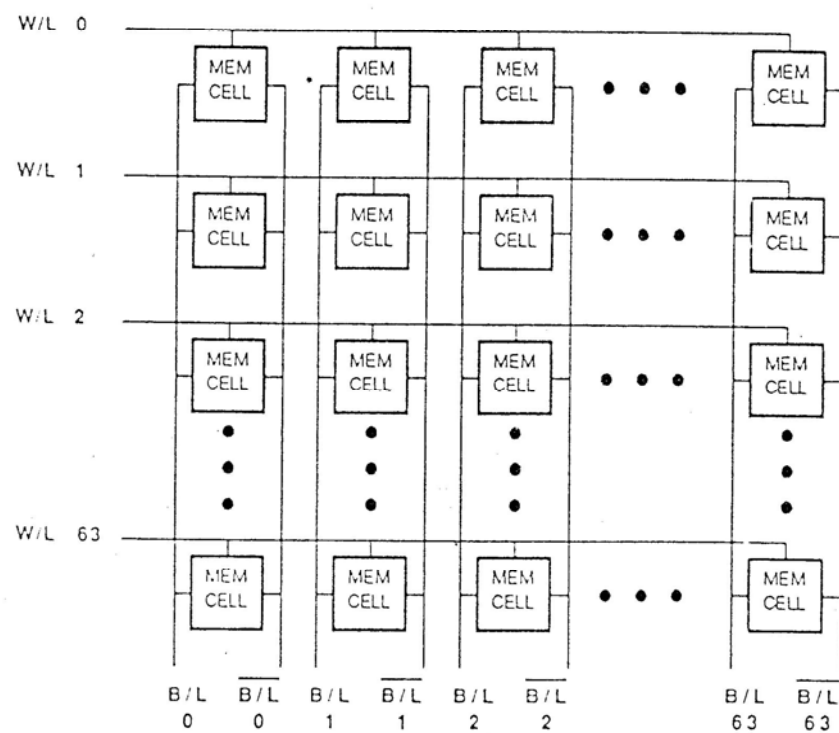
- Basic Architecture
- Storage Cell
- Address Decoding
- Data Sensing
- READ/WRITE Control

1K X 4 SRAM BLOCK DIAGRAM



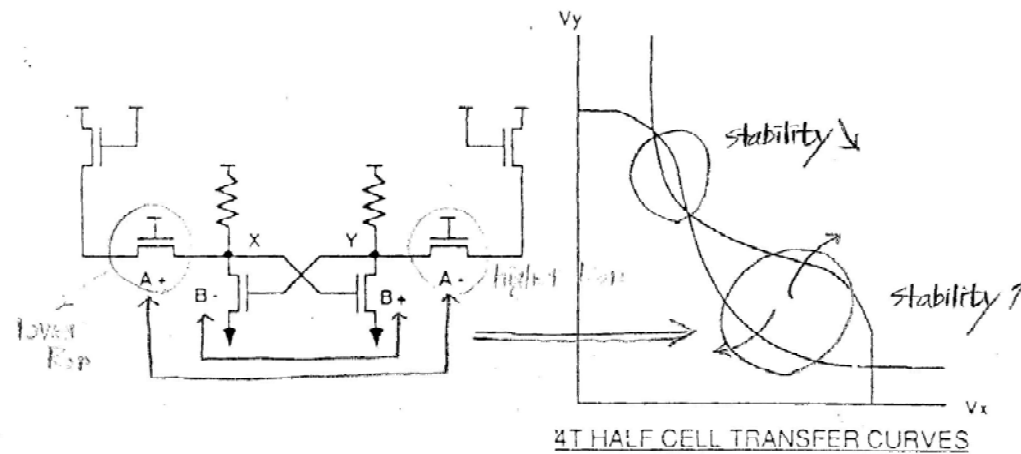
SRAM

4K SRAM MEMORY ARRAY



6T MEMORY CELL "READ" STABILITY

MEMORY CELL ASYMETRY

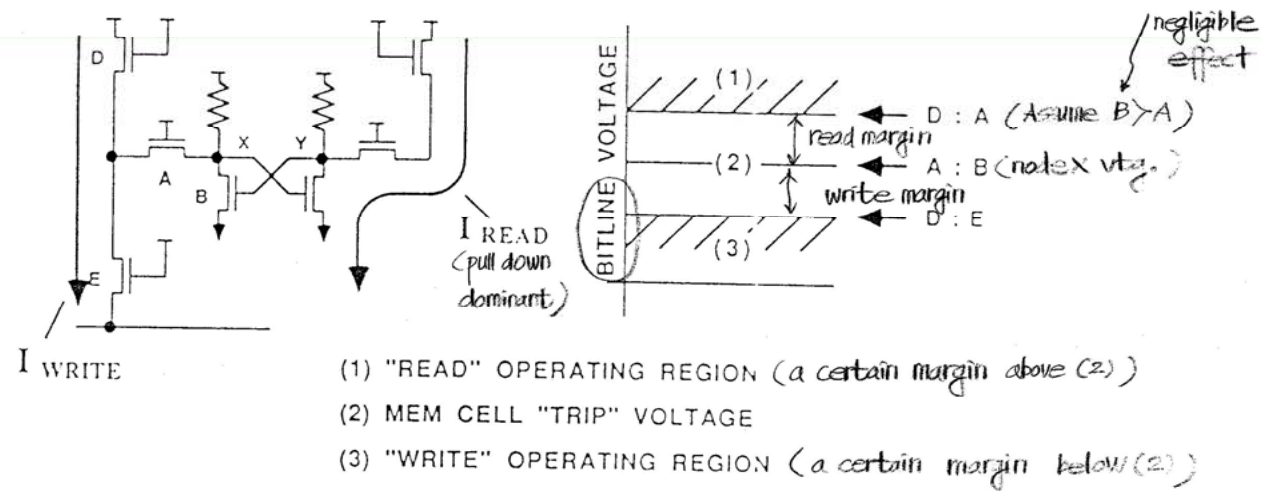


4T HALF CELL TRANSFER CURVES

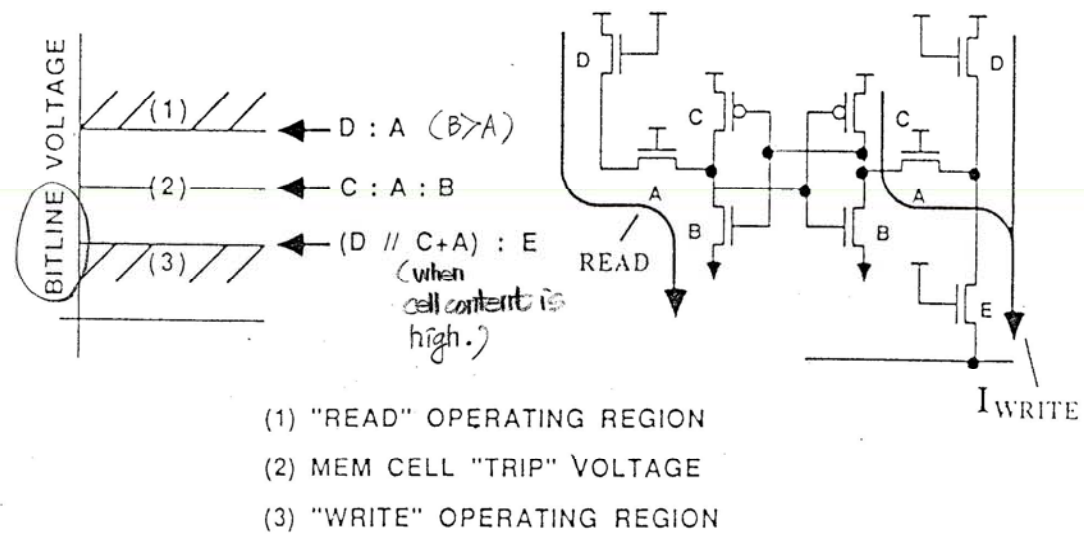
CAUSES:

- DESIGN MISMATCH - DIFFERENT LAYOUT/SIZE
 - PROCESS MISMATCH - V_t , C_D s, ETC
 - ALIGNMENT SENSITIVITY { WIDTH, LENGTH
- ↓ critical dimension

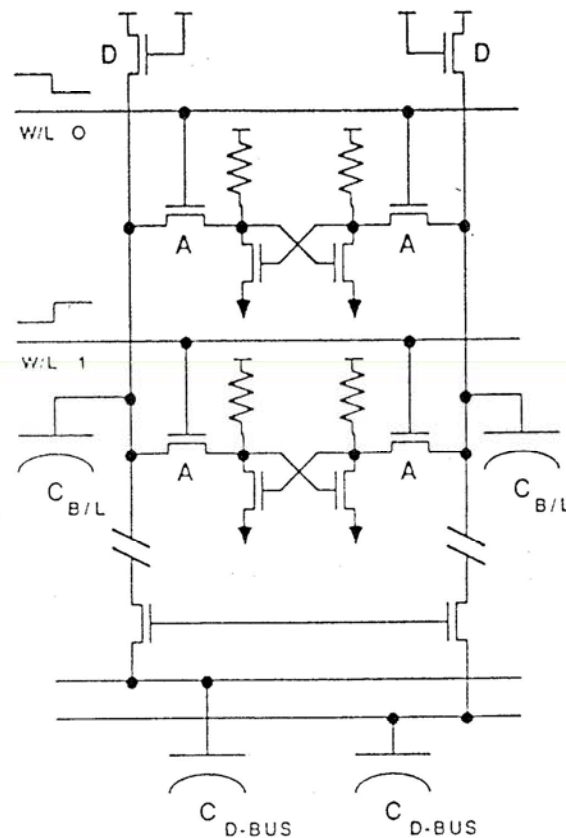
4T MEMORY CELL READ/WRITE OPERATION



6T MEMORY CELL READ/WRITE OPERATION



MEMORY CELL SPEED VR. POWER



$$Q = CV \rightarrow I_{\text{read}} \cdot dt = C_{\text{tot}} \cdot dV$$

$$dt = [C_{\text{tot}} / I_{\text{read}}] dV$$

"SPEED"

POWER
FIXED BY
PASS GATE
SIZE - A

CAP LOAD
FIXED BY
RAM DENSITY

VOLTAGE SWING
FIXED BY RATIO
D : A

DRAM - Dynamic Random-Access Memory

1988 IEDM Short Course on Microprocessor
and Memories

Nicky C.-C. Lu

 Research Division
Thomas J. Watson Research Center, Yorktown Heights, NY 10598

1. DRAM And Its Development

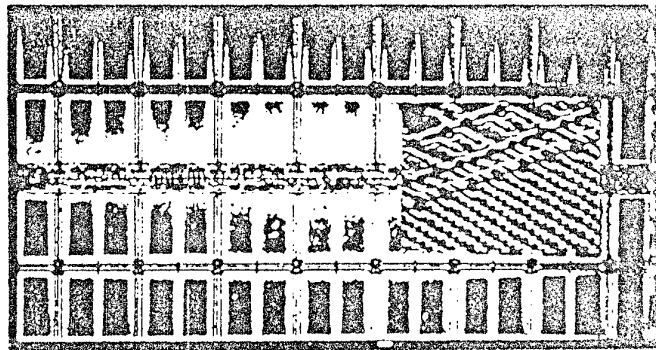
1.1 Background And Definition

1.2 DRAMs in Systems: Examples

1.3 Product Environments And Trends

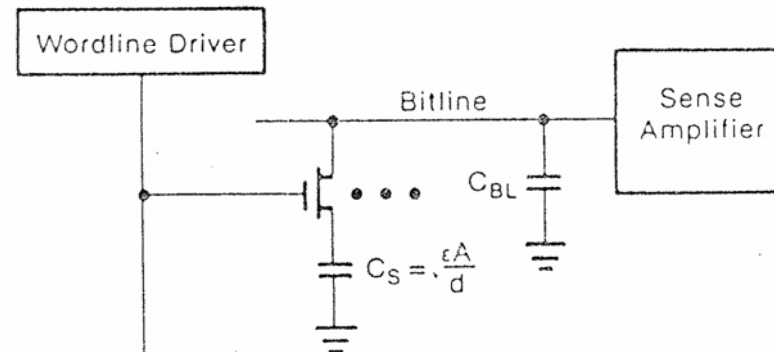
DRAM Chip

- Cell Arrays And Peripheral Circuits
- Array Utilization = $(\text{Cell Area} \times \text{Total Bits}) / (\text{Chip Area})$
- Key: Small Cell Area



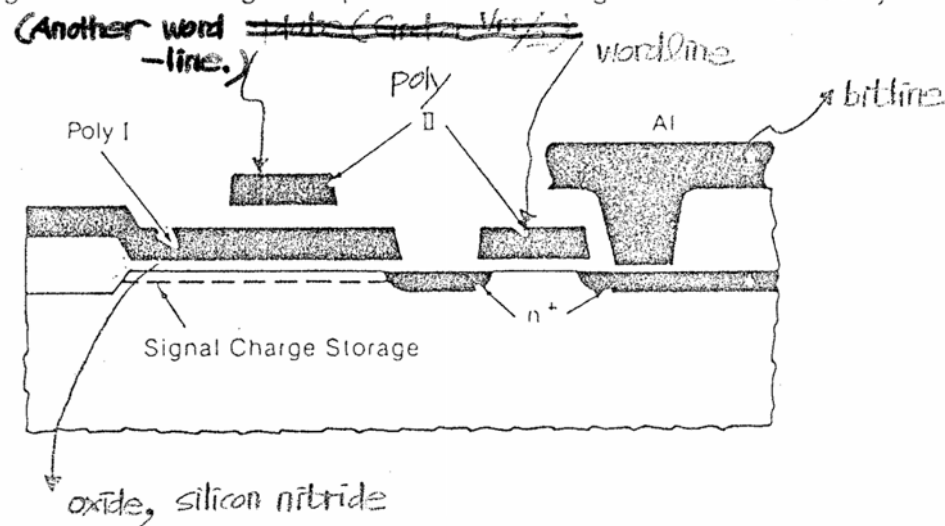
One-Transistor Cell

- An Access Transistor Plus A Storage Capacitor
 - Selected By Wordline
 - Signal Developed on Bitline



Planar Cell Structure

- Planar Transistor Plus Planar Capacitor in Silicon
- Uses Two Polysilicon Layers
- Storage-Node Leakage Requires Refreshing Data Periodically

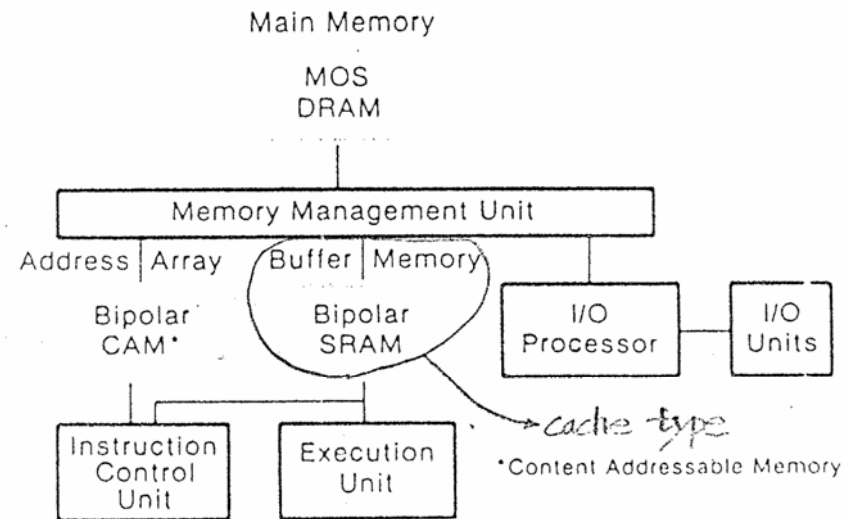


DRAM Definition

- Randomly Addressable Memory (Versus Serial Memory)
- Electrically Read and Write Data at Will in Any Sequence
- Needs Refresh Periodically
- Volatile (Unless By Battery Backup)

DRAM in Mainframe

- Today: $\approx 1\text{GB}$ (8,000 1Mb DRAM Chips)
- By 1995: $\geq 64\text{GB}$ (Needs 8,000 64Mb DRAM Chips)



(Figure from Ref. B-6)

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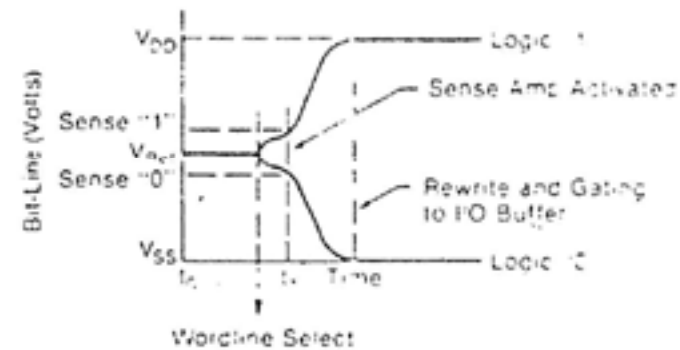
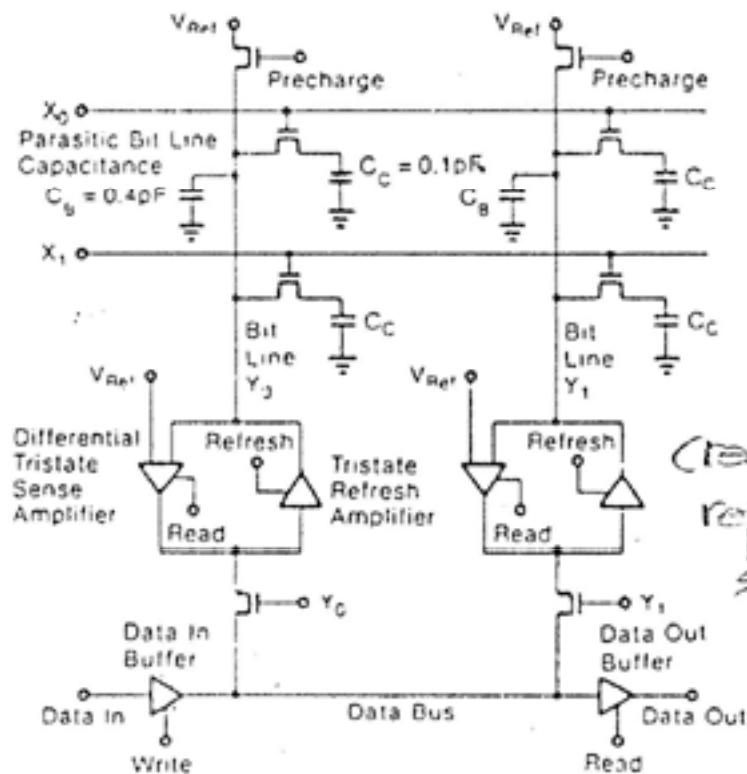
2. Chip/Circuit Design

2.1 Basic DRAM Operations

2.2 Design Example: A 512Kb CMOS High Speed DRAM

2.3 Notes on NMOS and BiCMOS DRAMs

Basic Array Design

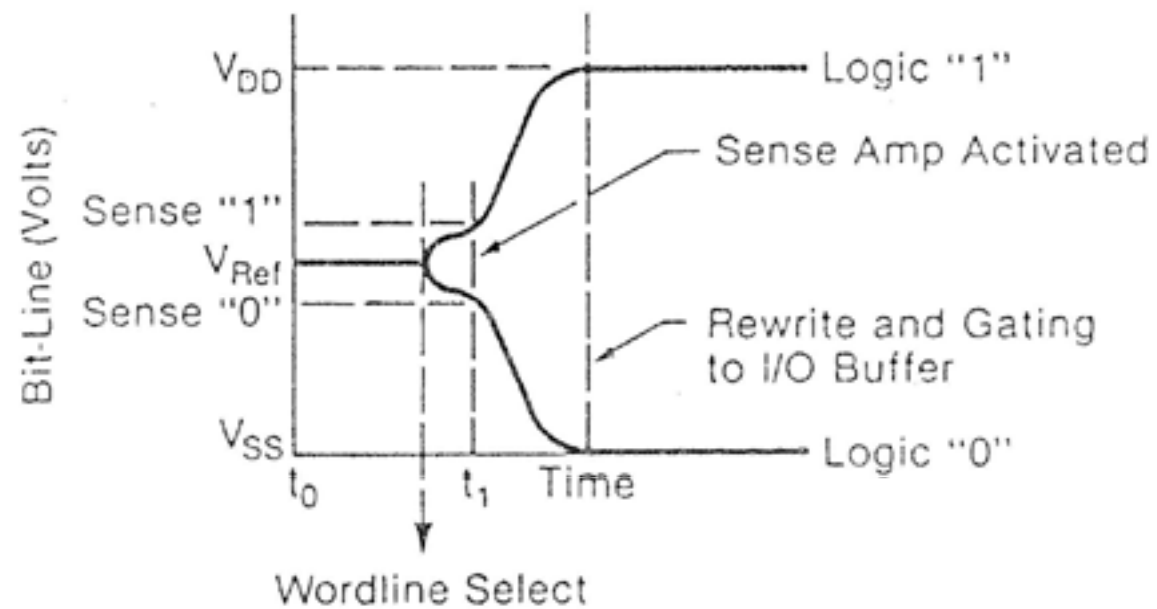


(read & refresh simultaneously.)

(After Ref.)

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Signal Development



Charge Transfer Ratio Concept

- $V_R(1) = \frac{C_s V(1) + C_B V_{ref}}{C_s + C_B}$ (**charge sharing**) C_s ; cell cap.
 C_B ; bit-line cap.
- $\Delta V_{sen}(1) = V_R(1) - V_{ref} = \frac{C_s}{C_s + C_B} [V(1) - V_{ref}]$
- $\Delta V_{sen}(0) = V_{ref} - V_R(0) = \frac{C_s}{C_s + C_B} [V_{ref} - V(0)]$
- $V_{sen} = \frac{1}{2} [\Delta V_{sen}(1) + \Delta V_{sen}(0)] = \frac{1}{2} \underbrace{\left(\frac{C_s}{C_s + C_B} \right)}_{\approx C_B, (1:10)} \underbrace{[V(1) - V(0)]}_{V_s}$
(average value)
- Transfer Ratio $T = \frac{C_s}{C_s + C_B}$
- Storage Charge Capacity $Q_s = C_s V_s = 2(C_s + C_B) V_{sen}$

$$V_{sen} = \frac{C_s V_s}{2(C_s + C_B)} \approx \frac{V_s}{2(1 + C_B/C_s)}$$

$V_s \uparrow$ or $C_B/C_s \downarrow$

Cell Design Basics

- $V_{\text{sen}} + \Delta V = \frac{1}{2(C_S + C_B)} \cdot \frac{\epsilon A V_S}{d}$

Where ΔV : Noise

ϵ : Dielectric Constants

A : Storage Area

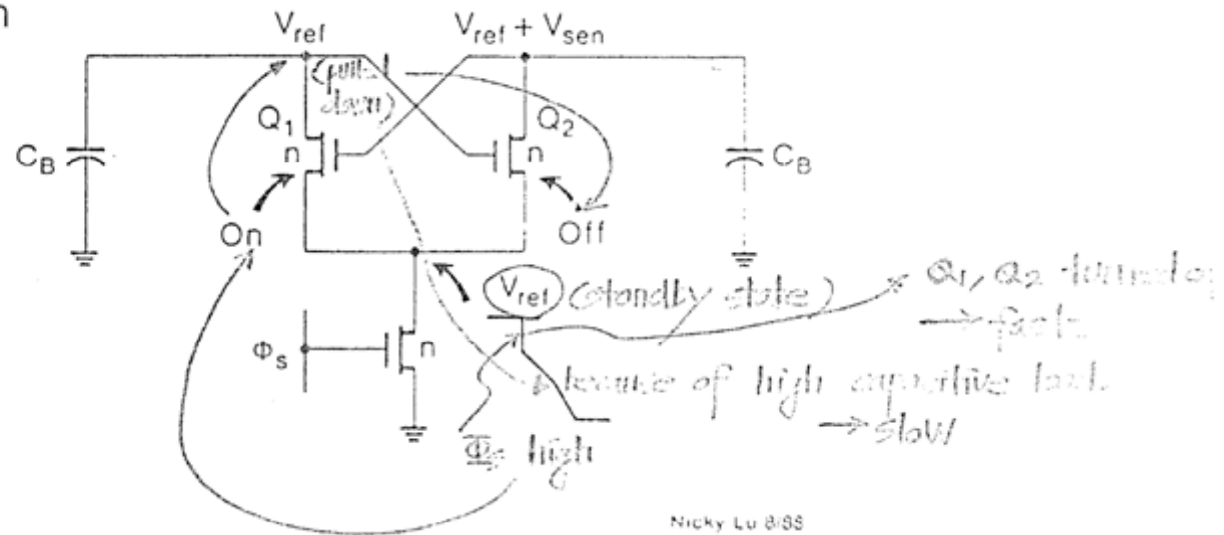
V_S : Storage Signal

d : Dielectric Thickness

- V_S/d Limited By Maximum Dielectric Strength

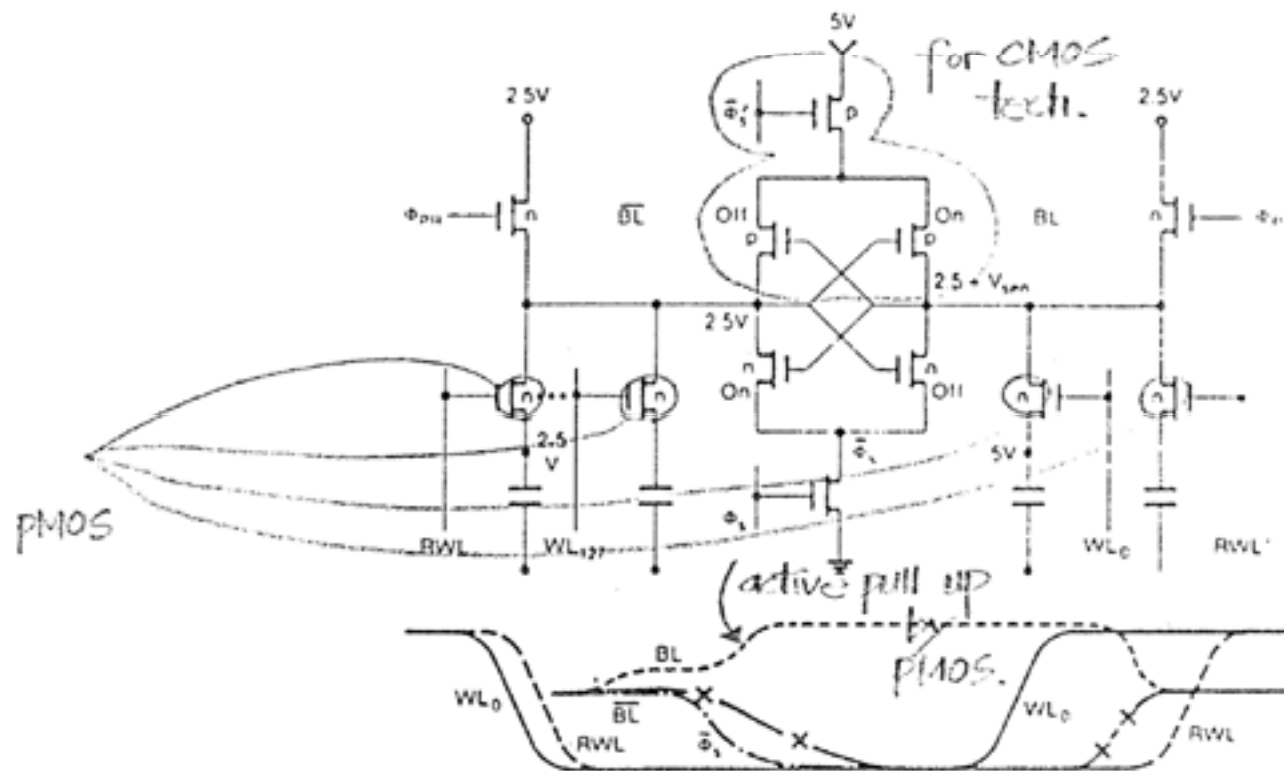
Cross-Coupled Sense Amplifier

- Differential Signal Established
- Latching
- Amplification



Sensing Circuits

- CMOS Cross-Coupled Latch

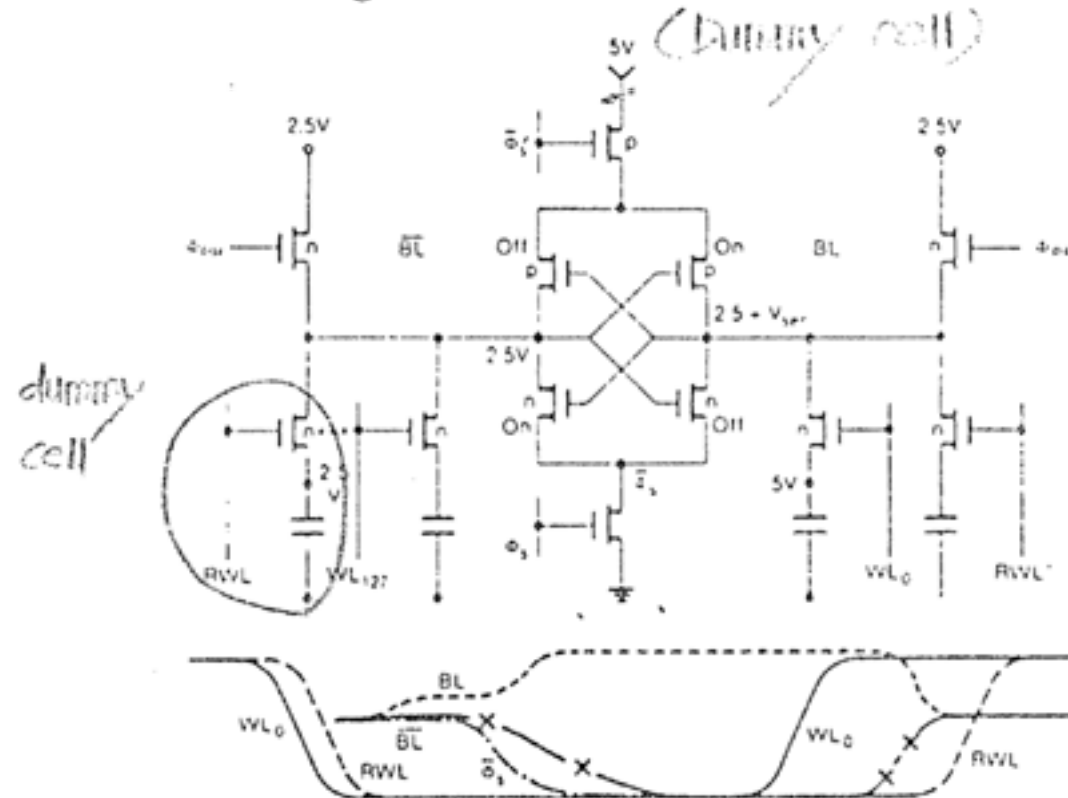


Sensing Circuits

- Bitline Precharge

- Reference Cell Concept

($V_{L0} = -1.2V$)
 → the same coupling to other lines.



Sensing Circuits

- Self Restore
- Refresh

